

In the Specification:

Please amend the specification at Page 7, lines 7-17 as follows:

Finally, Figure 1H illustrates yet other embodiments of the present invention. In these embodiments, the cavity **170** may be filled with an encapsulant **180**, such as epoxy and/or other optical coupling media (e.g., silicon). The encapsulant **180** can enhance optical coupling from the light emitting device **160** to the transparent inner core **150**. The design and fabrication of mounting substrates **170** that may be used in some embodiments of the present invention, are described in concurrently filed U.S. Patent Application Serial No.

 10/659,108 to Negley, entitled *Solid Metal Block Mounting Substrates for Semiconductor Light Emitting Devices, and Oxidizing Methods for Fabricating Same* (~~Attorney Docket 5308-311~~), assigned to the assignee of the present application, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.